

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10623788
<b>Filing Date:</b>	21-Jul-2003
<b>Title of Invention:</b>	Strained semiconductor by full wafer bonding
<b>First Named Inventor/Applicant Name:</b>	Leonard Forbes
<b>Filer:</b>	Robert Madden/Lisa Posorske
<b>Attorney Docket Number:</b>	1303.109US1

Filed as Large Entity

Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				790